

Electronic Patent Application Fee Transmittal

Application Number:	10562356			
Filing Date:	27-Dec-2005			
Title of Invention:	RESIN SEALING METHOD FOR ELECTRONIC PART AND MOLD USED FOR THE METHOD			
First Named Inventor/Applicant Name:	Shinji Takase			
Filer:	Charles Gorenstein/Patti Young			
Attorney Docket Number:	0033-1048PUS1			
Filed as Large Entity				
U.S. National Stage under 35 USC 371 Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Utility Appl issue fee	1501	1	1510	1510
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Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension-of-Time:				
Miscellaneous:				
Printed copy of patent - no color	8001	4	3	12
Total in USD (\$)				1822